



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Shizuka UEHARA et al.

Group Art Unit: 1655

Appln. No. : 10/531,289
(National Stage of PCT/JP2003/09651)

Examiner: Hoffman

I.A. Filed : July 30, 2003

Confirmation No: 4829

For : EXTERNAL PREPARATION FOR SKIN AND METHOD OF USING THE
SAME

**DECLARATION UNDER 37 C.F.R. 1.132
CONCERNING SPELLING OF CISTUS MONSPELIENSIS L.**

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

I, the undersigned, Taku HOSHINO, citizen of Japan, do solemnly declare as follows:

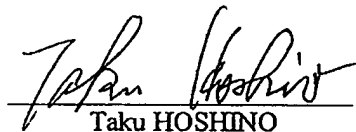
1. That I am a co-inventor of the above-identified application.
2. That I have reviewed the Final Office Action mailed October 9, 2008 as well as the application that was filed in connection with the above-identified application when entering the national stage in the U.S. on April 14, 2005, published as WO 2004/041236 A1 (and hereinafter referred to as "the originally filed application") and the Amendment Under 37 C.F.R. 1.111 in Response to Office Action Mailed March 28, 2008 (hereinafter "Amendment").
3. That I have reviewed U.S. Patent No. 6,313,214 B1 that is cited in the Final Office Action.
3. That the term "Cistus monoperiensis L." appearing in specification is an incorrect spelling of the academic name, with the correct academic name being "Cistus monspeliensis L."

4. That the term in the originally filed application is a misspelling of the correct academic name which is "Cistus monspeliensis L." and the Amendment includes the correct spelling.

5. That it is believed that the term "Cistus monoperiensis L." appearing in U.S. Patent No. 6,313,214 B1 is also a misspelling of the correct academic name "Cistus monspeliensis L.".

The undersigned further declares that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the above-captioned application or any patent issuing thereon.

2009.03.06
Date


Taku HOSHINO